

ISFIT[®]

Wire to Board/Board to Board 4점 접점 Press fit 단자

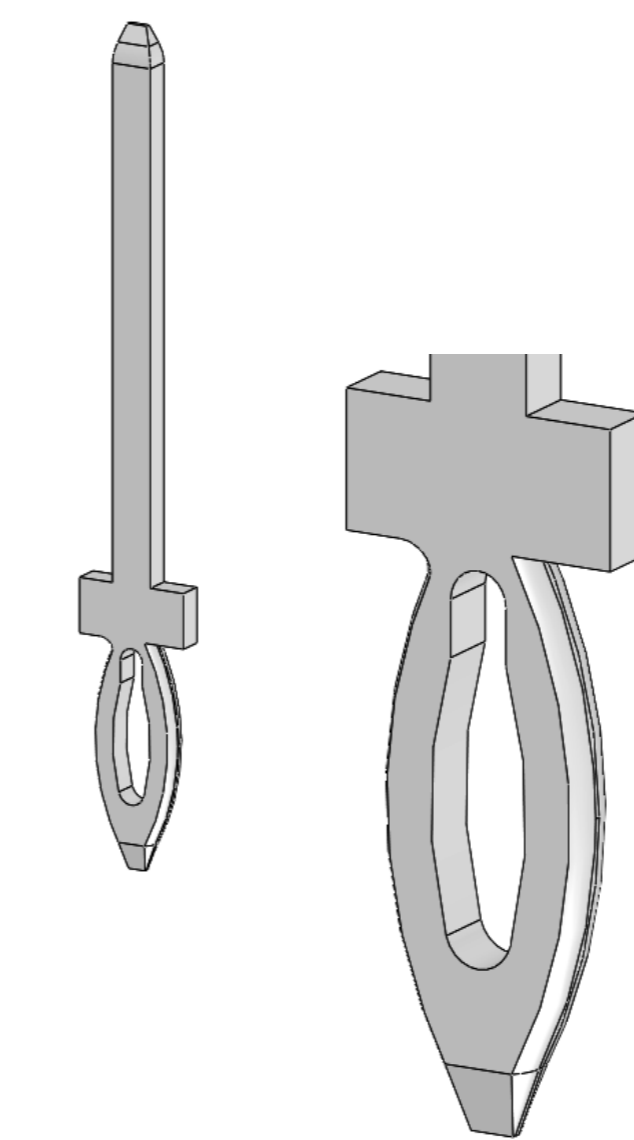
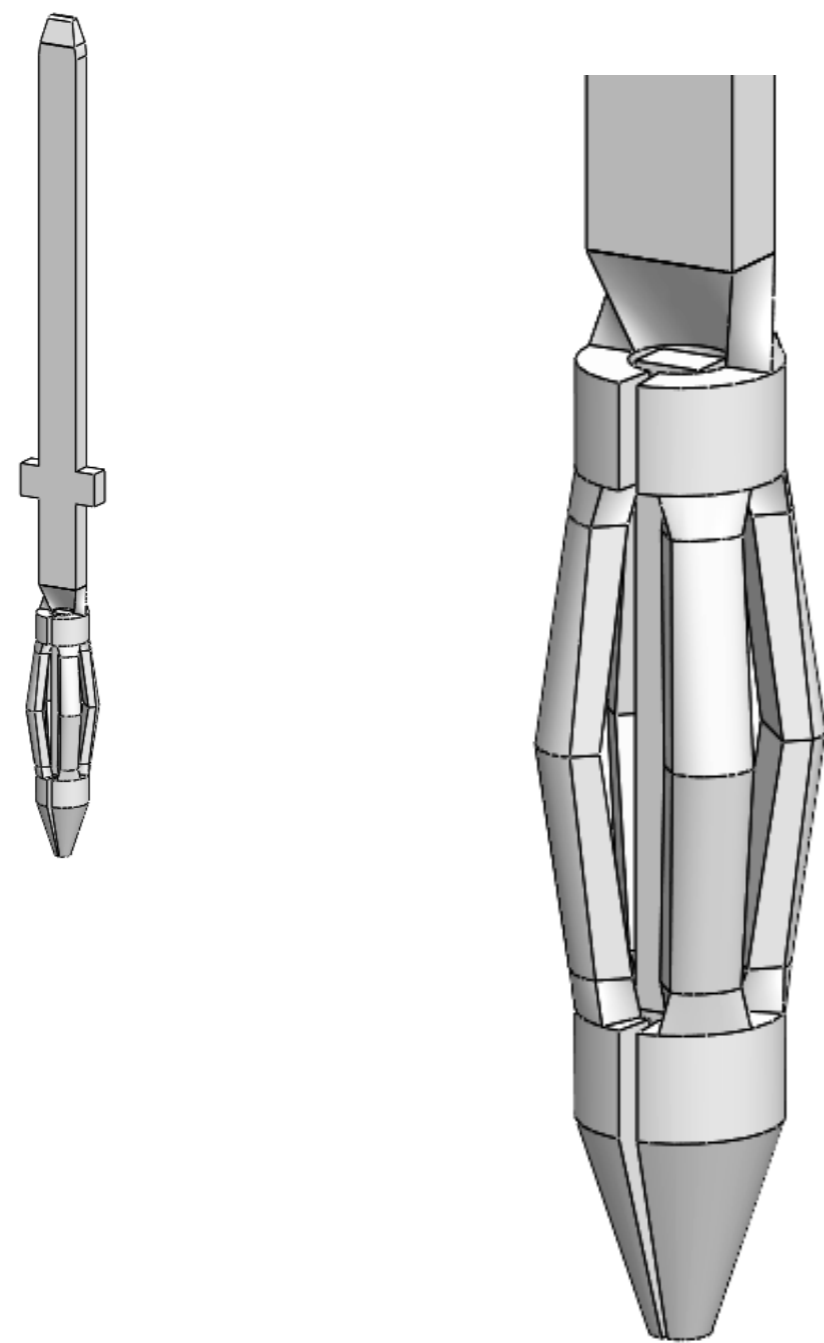
Product Specifications:

Operating Temperature	-40 - 125°C
Material	-40 - 85°C : NB109-EH Reflow Sn plating (0.8-1.5 μm) -40 - 125°C : C7025-TM02 Reflow Sn (0.8-1.5 μm)
Through-hole Size	Φ1.00 ± 0.05 mm, Φ1.20 ± 0.05 mm, Φ1.60 ± 0.05 mm (Cu plating 25 μm or thicker)
Vibration Resistance	20 G (depends on insertion condition to PCB)
Current Rating	5A (depends on size of terminal)

사진,도면의 커넥터는 ISFIT단자의 실장된 상태예시입니다.
요구에 맞추어, 이 Terminal을 사용한 다양한 Customized 커넥터를 제안 드립니다.
[자세한 내용은 문의를 주시기 바랍니다.](#)
ISFIT단자의 라인업은 아래 매트릭스표를 참조해 주십시오.



▶ 4점 Spring 접점방식 설계

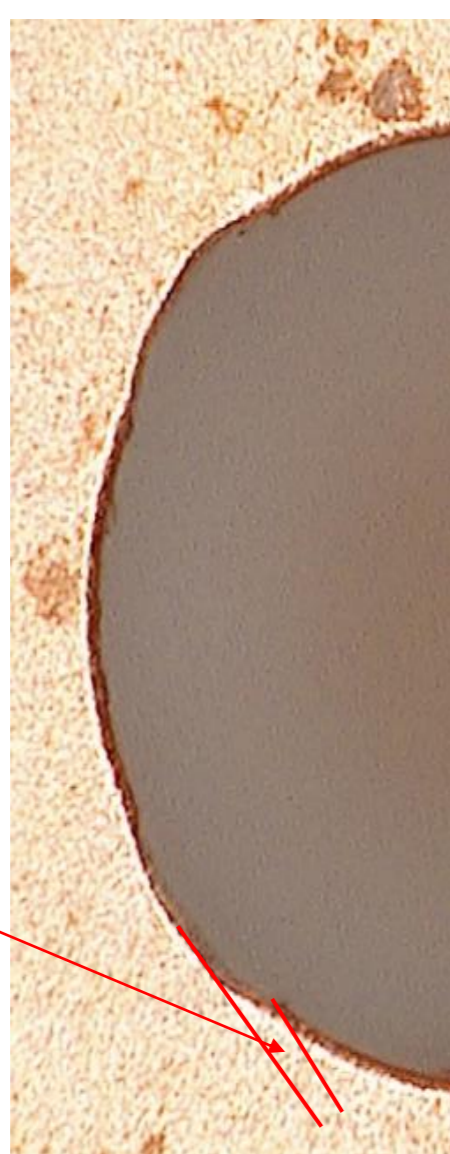


종래의 Needle eye방식

▶ 기판 데미지의 큰 폭 경감

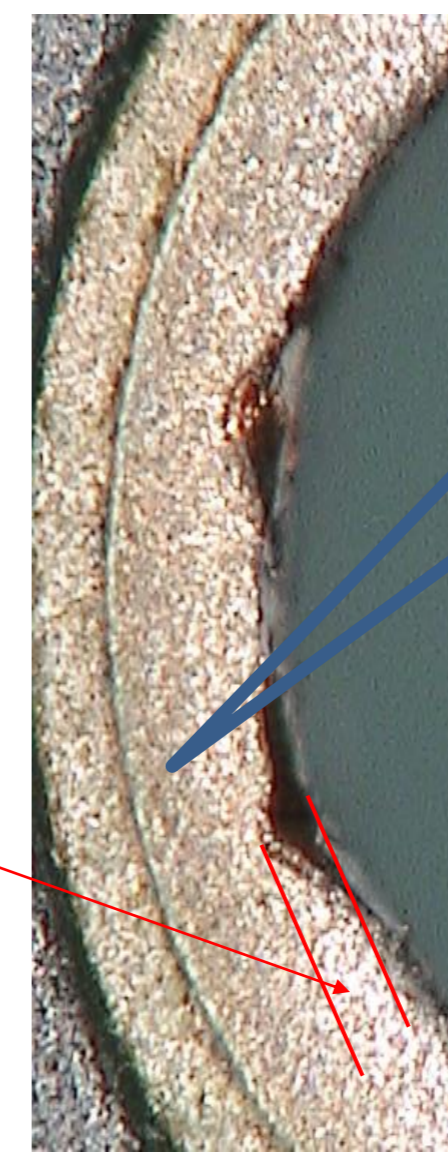
기판 Through hole 확대비교

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0.01mm

종래품



0.05mm

도금 벗겨짐

Spring구조단자로 인한 40N/pin max.의 낮은 삽입력.

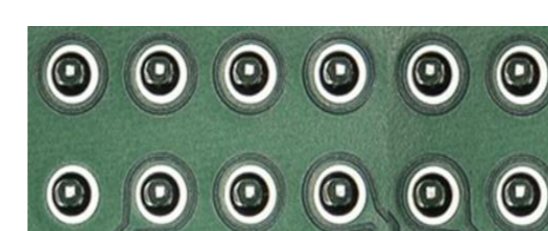
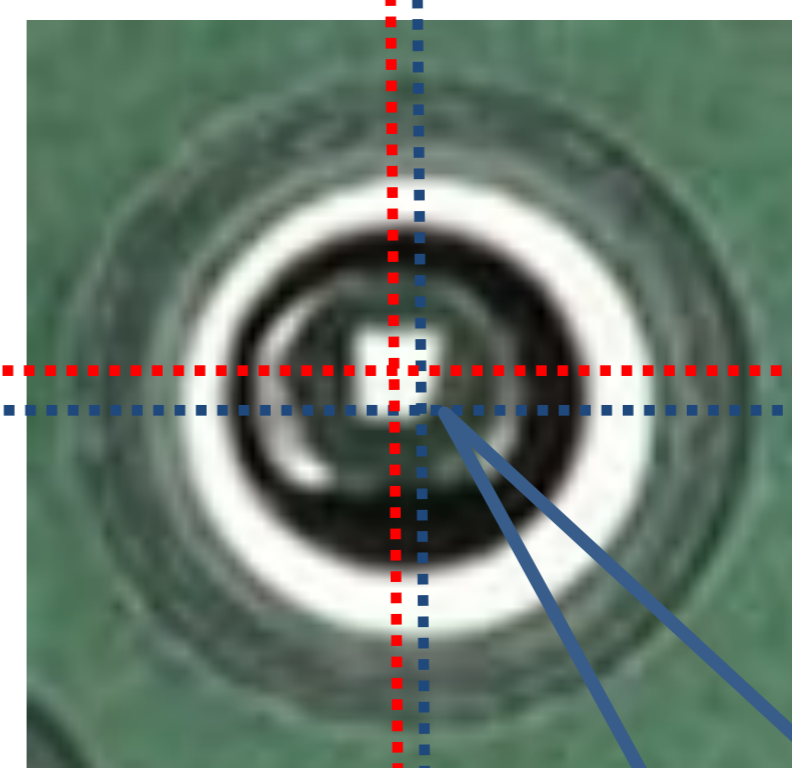
▶ 압입시의 위치어긋남을 흡수

ISFIT[®]



단자와 Through hole의 중심이 일치함

종래품



단자와 Through hole의 중심이 어긋나 있음

..... 단자의 중심
..... Through hole의 중심

Series	ISFIT							
Type	Wire to Board					Board to Board		
Feature								
	Wire to Board type press fit terminal					Board to Board type press fit terminal		
Terminal Size(mm)	0.50 (Thickness : 0.40)	0.64 (Thickness : 0.25)	1.20 (Thickness : 0.30)	2.80 (Thickness : 0.30)	9.50 (Thickness : 0.64)	- (Thickness : 0.30)		
Through-hole Diameter(mm)	$\Phi 1.20 \pm 0.05$	$\Phi 1.20 \pm 0.05$	$\Phi 1.20 \pm 0.05$	$\Phi 1.60 \pm 0.05$	$\Phi 1.50 \pm 0.05$	$\Phi 1.00 \pm 0.05$	$\Phi 1.20 \pm 0.05$	$\Phi 1.60 \pm 0.05$
PCB Material	FR-4 (1.6mm) $T_g \geq 140^\circ\text{C}$, Cu plating min. 25 μm required on through-hole							
Insertion Force *1	40N / hole							
Retention Force *1	5N / hole							
Current Rating *2	4.5A	7.0A	14A	25A	30A	4.5A	4.5A	7.0A
Vibration *2	20G							
Operating Temperature	-40 - 125 $^\circ\text{C}$							

*1 Specifications will vary depending on through-hole diameter

*2 Results from Board-to-Board prototype. Specifications will vary depending on testing conditions.

Board to Board



High-Density



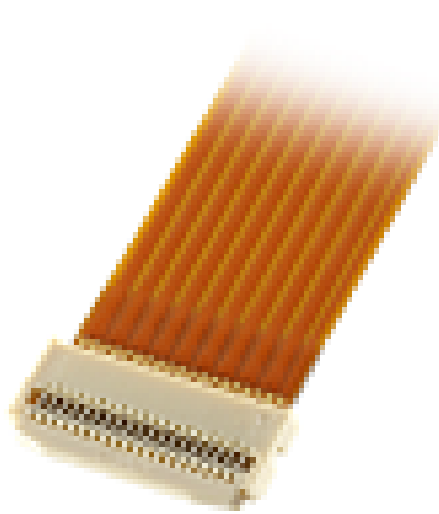
Autolocking FPC/FFC



High-Density



FPC/FFC



Micro-Coaxial / Discrete Cable



High-Speed



RF



High-Frequency



Optical Module



High-Speed



Effector



I/O (Input/Output)



Quick charge



High-Power



Custom Connectors Available

Inquiry



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